900216416 03/02/2012

TRADEMARK ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	Release Of Security Interest In Intellectual Property Collateral

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
JPMorgan Chase Bank, N.A., as Administrative Agent		02/29/2012	National Association: UNITED STATES

RECEIVING PARTY DATA

Name:	The Matrixx Group Incorporated
Street Address:	15000 U.S. Highway 41 North
City:	Evansville
State/Country:	INDIANA
Postal Code:	47725
Entity Type:	CORPORATION: INDIANA

Name:	Bulk Molding Compounds, Inc.
Street Address:	1600 Powis Court
City:	West Chicago
State/Country:	ILLINOIS
Postal Code:	60185
Entity Type:	CORPORATION: ILLINOIS

Name:	Citadel Intermediate Holdings, LLC
Street Address:	150 N. Radnor Chester Road, Suite F-200
City:	Radnor
State/Country:	PENNSYLVANIA
Postal Code:	19087
Entity Type:	LIMITED LIABILITY COMPANY: DELAWARE

PROPERTY NUMBERS Total: 4

Property Type	Number	Word Mark
Registration Number:	3191296	BMC
Registration Number:	3188753	BMC

OP $115.00 3191296

Registration Number:	0584332	GLASKYD
Serial Number:	77745145	SUSTAINALLOY

CORRESPONDENCE DATA

Fax Number: (617)951-8736
Phone: 617-951-8132
Email: linda.salera@bingham.com
Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.
Correspondent Name: Linda A. Salera
Address Line 1: 1 Federal Street
Address Line 2: c/o Bingham McCutchen LLP
Address Line 4: Boston, MASSACHUSETTS 02110

NAME OF SUBMITTER:	Linda A. Salera
Signature:	/Linda A. Salera/
Date:	03/02/2012

Total Attachments: 7
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RELEASE OF SECURITY INTEREST
IN INTELLECTUAL PROPERTY COLLATERAL

This **RELEASE OF SECURITY INTEREST IN INTELLECTUAL PROPERTY COLLATERAL** (this "**Release**"), dated as of February 29, 2012, is made by **JPMORGAN CHASE BANK, N.A.**, as agent (the "**Administrative Agent**"), under the Security Agreement referred to below (terms used in this Release and not herein defined shall have the meanings set forth in the Security Agreement).

WHEREAS, in connection with that certain Security Agreement, dated as of May 2, 2008 (as amended, restated, amended and restated, supplemented or otherwise modified from time to time, the "**Security Agreement**"), among **THE MATRIXX GROUP INCORPORATED**, an Indiana corporation, **BULK MOLDING COMPOUNDS, INC.,** an Illinois corporation (collectively referred to herein as the "**Borrowers**"), and **CITADEL INTERMEDIATE HOLDINGS, LLC**, a Delaware limited liability company (the "**Parent**"), the financial institutions from time to time party thereto as "**Lenders**", and **JPMORGAN CHASE BANK, N.A.**, as agent (the "**Administrative Agent**").

WHEREAS, in connection with the Security Agreement, and pursuant to those certain agreements described on Annex I attached hereto (collectively, the "**Assignment Agreements**"), certain Borrowers granted security interests in certain intellectual property including those listed on Annex I attached hereto (collectively, the "**Intellectual Property Collateral**"); and

WHEREAS, the Assignment Agreements were recorded in the U.S. Patent and Trademark Office or the Copyright Office on the dates and on the reels and frames set forth on Annex I hereto;

NOW THEREFORE, the Administrative Agent hereby **RELEASES,** without representation, recourse or warranty whatsoever, all of its security interest in the Intellectual Property Collateral, whether granted pursuant to the Security Agreement or the Assignment Agreements, and the Administrative Agent hereby reassigns any and all such right, title and interest (if any) that the Administrative Agent may have in the Intellectual Property Collateral to the Borrowers.

This Release and the rights and obligations of the parties hereto shall be governed by, and construed and interpreted in accordance with, the laws of the State of New York.

[Signature Page Follows]

IN WITNESS WHEREOF, the Administrative Agent has executed this Release as of the date first above written.

JPMORGAN CHASE BANK, N.A.,
as Administrative Agent

By: ______________________
Name: [illegible]
Title: Authorized Officer

[Signature Page to Release of Security Interest in Intellectual Property Collateral]

ANNEX I

The Assignment for Security Patents, dated as of May 2, 2008, by Bulk Molding Compounds, Inc. in favor of JPMorgan Chase Bank, N.A., was recorded with the U.S. Patent and Trademark Office on May 3, 2008 at Reel/Frame No. 020897/0056.

Patent and Patent Applications

1. United States Patent No. 6,576,170 B1 for Gas-Assisted Injection Molding of Thermosetting Polymers dated June 10, 2003 naming BMCI as Assignee.

2. United States Patent No. 7,047,626 B2 for Encapsulated Electronically Resistive Heater dated May 23, 2006 naming BMCI as Assignee.

3. United States Patent No. 6,933,333 B2 for Conductive Adhesive Sealant for Bipolar Fuel Cell Separator Plate Assemblies dated August 23, 2005 naming BMCI as Assignee.

4. French Patent No. 97 12 807; PCT/FR 98/02194 for Bulk Molding Compound Composite Material and Method for the Manufacture of the Material dated October 14, 1997.

5. Exclusive Patent License Agreement No. 01-41-01146 by and between the Regents of the University of California and BMCI dated September 18, 2001 relating to the license of United States Patent No. 6,248,467 B1 for Composite Bipolar Plate for Electrochemical Cells dated June 19, 2001 naming the Regents of the University of California, Los Alamos, NM (US) as assignee.

The Assignment for Security Trademarks, dated as of May 2, 2008, by Bulk Molding Compounds, Inc. in favor of JPMorgan Chase Bank, N.A., was recorded with the U.S. Patent and Trademark Office on May 3, 2008 at Reel/Frame No. 003771/0370.

Trademarks and Trademark Applications

	Mark	App. / Reg. No.	Country	Registration/Application Date
1.	BMC Logo	Registered 1047521	Australia	March 22, 2005
2.	Bulldog Logo	Registered 1047300	Australia	March 22, 2005
3.	BMC Logo	Application Pending 837360827	Brazil	April 27, 2005
4.	Bulldog Logo	Application Pending 827360835	Brazil	April 27, 2005
5.	BMC Logo	Registered TMA662,223	Canada	April 5, 2006
6.	Bulldog Logo	Registered TMA661,135	Canada	March 22, 2006
7.	BMC Logo	Application Pending 4574798	China (Peoples Republic)	March 31, 2005
8.	Bulldog Logo	Application Pending 4574799	China (Peoples Republic)	March 31, 2005
9.	BMC Logo	Registered 004438289	European Community	March 5, 2006
10.	Bulldog Logo	Registered 004438305	European Community	March 5, 2006
11.	BMC Logo	Registered 300387081	Hong Kong	March 17, 2005
12.	Bulldog Logo	Registered 300380538	Hong Kong	March 4, 2005
13.	BMC Logo	Serial No. 2005-024739 (Application denied; appeal pending)	Japan	March 22, 2005
14.	Bulldog Logo	Registered 5116858	Japan	March 7, 2008
15.	BMC Logo	Published 1357256	India	May 16, 2005

	Mark	App. / Reg. No.	Country	Registration/Application Date
16.	Bulldog Logo	Registered 1357257	India	May 16, 2005
17.	BMC Logo	Registered 656444	Korea, Republic of	March 24, 2005
18.	Bulldog Logo	Registered 656445	Korea, Republic of	March 24, 2005
19.	BMC Logo	Registered 974291	Mexico	February 26, 2007
20.	Bulldog Logo	Registered 916217	Mexico	January 24, 2006
21.	BMC Logo	Registered 304614	Russian Federation	April 11, 2006
22.	Bulldog Logo	Registered 304341	Russian Federation	April 6, 2006
23.	BMC Logo	Registered 535.122	Switzerland	March 29, 2005
24.	Bulldog Logo	Registered 535.084	Switzerland	March 29, 2005
25.	BMC Logo	Registered 1176875	Taiwan	October 16, 2005
26.	Bulldog Logo	Registered 1176876	Taiwan	October 16, 2005
27.	BMC Logo	Registered 200512388	Turkey	April 6, 2005
28.	Bulldog Logo	Registered 200512389	Turkey	April 6, 2005
29.	BMC Logo	Registered 3,191,296	United States of America	January 2, 2007
30.	Bulldog Logo	Registered 3,188,753	United States of America	December 26, 2006

	Mark	**App. / Reg. No.**	**Country**	**Registration/Application Date**
31.	GLASKYD	Registered 584,332	United States of America	January 1, 1954 (renewal date: January 5, 2014)

The Assignment for Security Trademarks, dated as of July 19, 2010, by Matrixx-QTR, Inc. in favor of JPMorgan Chase Bank, N.A., was recorded with the U.S. Patent and Trademark Office on July 20, 2010 at Reel/Frame No. 004245/0683.

	Mark	**App. / Reg. No.**	**Country**	**Registration/Application Date**
1.	SUSTAINALLOY	Application pending 77/745,145	U.S.	May 27, 2009